## Report Information

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# High Density Interconnect PCB Market Research Report – Forecast 2027

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**Description:**

# High Density Interconnect PCB Market Overview

In 2018, the global high-density interconnect PCB market value is registered as USD 8,683.9 million and is expected to grow at a significant CAGR of 12% with the high density Interconnect market size of USD 15,600.6 million during the forecast period 2018- 2023. In PCBs, high-density interconnect PCB is one of the fastest-growing technology. It has a higher circuitry density compared to the traditional PCB, hence this device allows the designers to place more components on both sides of the raw PCB if desired. It contains blind and buried vias and also contains micro-vias with less diameter of 0.006 or less. The higher density allows the designers to place smaller size components with a shorter distance between them that helps in reduced signal loss and crossing delays which leads to transmits signals faster from one component to another. This device can reduce the weight and overall dimensions of the product and also enhance the electrical performance of the device.

There is a high need for energy-efficient, smaller, and high-performance PCBs which increases the high-density interconnect PCB market. This leads to producing smarter, smaller, lighter, and faster products by the overall electronics industry. These high-density interconnect PCBs are highly preferred in various electronic devices like touch-screen devices, mobile phones, laptop computers, digital cameras, and 4G network communications. It is also mostly featured in medical devices and equipment, various electronic aircraft parts, and components. The possibilities for this technology seem almost limitless.

**COVID-19 Analysis:**

The COVID-19 pandemic is spread all over the world and impacts all business sectors. To control the spread of the virus, most governments implemented lockdowns and stringent rules on the public like transportation bans, public places closed, manufacturing industries shut down, and limited timings for retailer businesses. Due to these factors, manufacturing industries face a lot of issues like supply disruptions, lack of raw materials, and shortage of workers which leads to a stoppage of production.

These factors lead to the global economic recession. The electronics industry is drastically impacted due to the pandemic. Most of the electronic components are imported from China which is severely impacted by the COVID-19. So, the lack of raw materials imported from China delays the production of High density interconnect PCBs. Hence the high-density interconnect PCB market is also negatively impacted. Further, rapidly the growth of the market increases by the lifting of lockdowns and reducing corona cases. By introducing the new technologies, the market growth is expected to increase in the coming years.

**Market Dynamics:**

- **Drivers:**

The growing sales of consumer electronics, rising need for energy-efficient, smaller, lower weight, and high-performance PCBs are the factors driving the high-density interconnects PCB market growth. The rising trend towards sophisticated safety systems, autonomous driving, and miniaturization of electronic devices in the automobile sector is accelerating the growth of the market. The increasing need for consumer electronic devices with good power performance coupled with the larger color displays is demanding larger battery space and reducing the space for PCBs in these devices is boosting the growth of the global market.

HDI PCB has various advantages like minimum materials and boards for its composition, increases efficiency compared to conventional PCBs, less construction time, faster production, increases device performance which is escalating the market growth.

- **Restraint:**

The manufacturing cost of high-density interconnects PCB is very expensive which is hindering the market growth.

- **Opportunities:**

The rise in the utilization of HDI PCB in the healthcare sector is predicted to create an opportunity to enhance the growth of the market. Moreover, rising awareness among the manufacturers regarding the higher circuitry density of HDI PCB compared to traditional PCB, because the HDI PCB allows designers to fit more components on it which is a high-density interconnects PCB market opportunity to the manufacturers for boosting the market growth. The

number of applications in the automotive industry like advanced driver assistance systems, GPS navigation, and infotainment is increasing the market growth.

- **Challenges:**

Lack of skilled expertise in the manufacturing of high-density interconnect PCB is the major challenge of the growth of the market.

**Study Objectives -**

- To provide detailed information about the high-density interconnect PCB market structure along with various forecast segments for the coming 7 years.
- To provide the impacting factors of the growth of the market value.
- To examine the high density interconnect PCB market industry analysis based on porter's five force analysis, supply chain analysis, etc.
- To provide previous and future revenue segments and sub-segments of the high density interconnect PCB market revenue for the four main geographies.
- To provide country-level analysis of the high density interconnect PCB market industry growth by region, form, high-density interconnection layer, application, and industry vertical.
- To offer an in-depth profile of the leading players in the market, study their core competencies, statistics, draw a global market growth landscape.
- To study and analyze new product developments, strategic alliances, mergers, acquisitions, and global market research.

**Segment Overview:**

The global high-density interconnects PCB market outlook has been divided into four segments based on high-density interconnection layer, application, industry vertical, and region.

**Based on the High-density Interconnection Layer**

The high-density interconnect layers are classified into 1, 2, and all.

**Based on Application**

The high-density interconnects PCBs by application is sub-segmented into various types as Touch-screen devices, mobile phones, laptop computers, digital cameras, engine control units, GPS, dashboard electronics, and 4G network communications. This is highly featured in medical devices and various electronic aircraft parts and components.

**Based on Industry Vertical**

The high-density interconnect PCB market analysis by industry vertical is categorized into various types such as automotive, consumer electronics, telecom & IT, military & defense, manufacturing, medical devices, and others. Among them, the consumer electronics segment is accounting for the largest market share due to the wide adoption of high-density interconnects PCBs in electronic applications like smartphones and computing market sectors. Moreover, the automotive segment is predicted to grow at a significant CAGR due to the rising digitalization of cars and its advanced technologies towards autonomous and connected cars.

**Based on Region**

Region-wise, the global high density interconnects PCB market is divided into four main geographies like Asia-Pacific, North America, Europe, and the Rest of the World. Among them, North America is dominating the largest market share due to the adoption of advanced technologies in the semiconductor field.

**Regional Analysis**

Geographically, the high-density interconnect PCB market based on regions is analyzed into four major regions such as North America, Europe, Asia-Pacific, and the Rest of the World. Out of these regions, North America is holding the highest high-density PCB market share due to the adoption of advanced innovative technologies in the semiconductor field. The high potential for revenue generation from the automotive and consumer electronics industry verticals is propelling the market growth in this region. The US is expected to hold a significant share during the forecast period.

Asia-Pacific is going to be the fastest-growing region due to the presence of several electronic devices manufacturing firms and the availability of low-cost technologies are the factors driving the global market in this region. In terms of market share, India, China, and Japan are the leading countries in this region and it is expected to continue in the review period.

**Competitive Landscape**

The prominent high density interconnect PCB market key players are the following:

- TTM Technologies (US)
- Millennium Circuits Limited (US)
- Mistral Solutions Pvt. Ltd. (India)

- Advanced Circuits (US)
- Fineline Ltd. (Israel)
- Epec, LLC (US)
- PCBCART (China)
- RAYMING (China)
- Sierra Circuits, Inc. (US)
- Fujitsu Interconnect Technologies Limited (Japan)
- Austria Technologie & Systemtechnik Aktiengesellschaft (Austria)

**Recent Developments**

In October 2017, the most popular enterpriser AT&S invested nearly USD 46.8 million to expand its technical competence. The plan of their project is to produce high-frequency PCBs for autonomous driving applications at their existing sites in India and Austria.

**High Density Interconnect PCB Market Report Overview:**

This global high density interconnects PCB market research includes the Market Overview, COVID-19 analysis, Market Dynamics, Study Objectives, Segment Overview, Regional Analysis, Competitive Landscape, Recent developments, Segmentation Table, and FAQs. The market scenario includes the high-density interconnect PCB market drivers, restraints, challenges, and opportunities. The high density interconnects PCB market forecast segments into four forms as high-density interconnection layer, application, industry vertical, and region.

**High Density Interconnect PCB Market Segmentation Table**

The high-density interconnects PCB market trends have been segmented into four forms globally based on the high-density interconnection layer, industry vertical, application, and region.

**By High-density interconnection layer**

1, 2, and all are the three interconnection layers.

**By Industry Vertical**

Automotive, consumer electronics, telecom & IT, military & defense, manufacturing, medical devices, and others are the various types of the market.

**By Application**

Touch-screen devices, mobile phones, laptop computers, digital cameras, engine control units, GPS, dashboard electronics, and 4G network communications are various applications.

**By Region**

Asia-Pacific, Europe, North America, and the rest of the world are the four main geographies included in the global market of the high density interconnect PCB.

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